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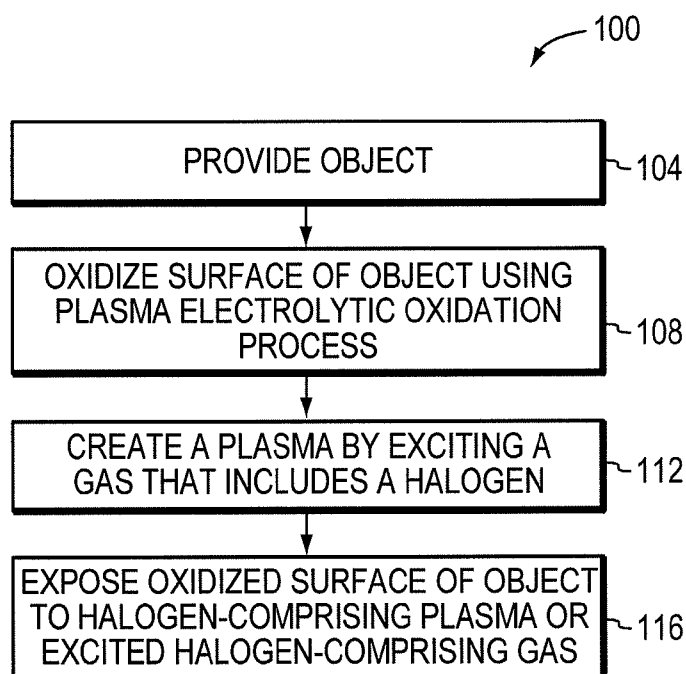
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(54) Title: METHODS AND APPARATUS FOR PROTECTING PLASMA CHAMBER SURFACES



(57) Abstract: A method for creating a protective layer over a surface of an object comprising aluminum and magnesium for use in a semiconductor processing system, which includes oxidizing the surface of the object using a plasma electrolytic oxidation process. The method also includes generating a halogen-comprising plasma by exciting a gas comprising a halogen. The method also includes exposing the oxidized surface to the halogen-comprising plasma or excited gas.

FIG. 1



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